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Title:Robust Large Dimension Terahertz Cloaking

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Abstract:Current interest in the pursuit of exotic electromagnetic properties has been motivated to a large extent by the recent work on invisibility cloaks. Transformation optics based on the invariance of Maxwell's equations and plasmonic cancellation based on the Mie scattering theory have brought the invisibility cloak into reality. The experimentally available cloaking designs have been demonstrated in the microwave, terahertz and optical regimes based on artificial metamaterials.

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Inspec controlled terms:electromagnetic wave propagation - invisibility cloaks - Maxwell equations - metamaterials - Mie scattering - plasmonics

Uncontrolled terms:terahertz cloaking - electromagnetic properties - invisibility cloaks - transformation optics - Maxwell's equations - plasmonic cancellation - Mie scattering theory - cloaking designs - metamaterials

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